2022 International Symposium on VLSI Design, Automation and Test (2022 VLSI-DAT)

The 2022 International Symposium on VLSI Design, Automation and Test will be held on April 18-21, 2022, at the Ambassador Hotel, Hsinchu, Taiwan. Original and unpublished papers on all aspects of VLSI Design, Automation and Test are solicited, including but not limited to:

ANALOG DESIGN	DIGITAL DESIGN	soc	EDA	TEST	AI APPLICATIONS
Biomedical Circuits	Communication Baseband Designs	CPU, DSP and Multicore Architectures	Analog EDA	3D IC and Interposer-Based IC Test	Specialized Hardware Architecture for AI
Energy-Harvesting and Power Management Circuits	Digital Circuits and ASICs	Embedded System and Software	Design for Manufacturability	Design-for-Testability and BIST	Hardware-efficient Al Methods
	Hardware Security and Trust	Multimedia Processing Designs	Design Verification	Memory Test	Compiler for Al Accelerators
Memristive and Neuromorphic Circuits	Low Voltage & Low Power Circuits Design	SOC and NOC Architectures	EDA for Microfluidic Biochips	On-Chip Monitoring	Al for EDA
RF, Analog and Mixed Signal Circuits	Memory Circuits and Systems	System-in-Package Designs	Electronic System Level Design	RF, Analog and Mixed-Signal Test	Al for Systems
Security Circuits for IoT and AI	Wired and IO Design		Hardware/Software Co-Design	Silicon Debug and Diagnosis	Systems for AI
Ultra Low-Power Circuits and Systems			Logic and Behavioral Synthesis	SOC and System Level Test	
			Physical Design and Verification	Yield and Reliability Enhancement	
			Modeling and Simulation	Test Generation and Compression	
			Power/Thermal Estimation and Optimization	Test Standards	

GENERAL INSTRUCTIONS

- Prospective authors are asked to submit their work in two stages for VLSI-DAT 2022.
 - → In Stage One (abstract submission), a title, an 80- to 100-word abstract, and a list of all co-authors must be submitted via the conference <u>submission page</u> before Nov. 01, 2021. No abstract submissions after the deadline.
 - → In **Stage Two** (paper submission), authors must electronically submit the self-contained paper with figures and tables via the same submission page before **Nov. 15, 2021**.
- The submitted manuscript must be 2-4 pages, double-columned, IEEE-style compatible, in PDF format only.

Any submissions not adhering to the rules will be rejected immediately without review.

- VLSI-DAT adopts the double-blind review process; please **DO NOT reveal** your name(s) or affiliation(s) anywhere in the submitted manuscript for the first paper submission.
- Before submitting your abstract/paper, please review the information on IEEE Intellectual Property Rights at https://www.ieee.org/web/publications/rights/index.html
- The notices of acceptance will be sent out to authors on December 30, 2021.
- Any changes on the title and author list or withdrawal after acceptance must be approved by Technical Program Co-Chairs.
- For an accepted paper to be published in the proceedings, one of its co-author(s) MUST register and attend the symposium to present the paper. Note that each accepted paper shall be accompanied by a distinct registration; that is, two registrations are required for presenting two papers even if the presenter is the same.
- Presentation of accepted papers at the symposium must be in English and limited to 18 minutes, with an additional 2 minutes for Q&A. The final manuscripts of all accepted papers will be published as submitted in the proceedings.
- No-show papers will not be included in the symposium proceedings and will not be submitted to the IEEE Xplore database.
- Please refer to the detailed information on the conference website for authors: https://expo.itri.org.tw/2022vlsidat

⇒ STUDENT SUBSIDY

Financial supports are available for full-time student presenters living outside of Taiwan.

⇒ BEST PAPER AWARD

Three best papers will be selected this year through a rigorous evaluation process conducted by the program committee and session chairs.

⇒ IMPORTANT DATES

Note: all are based on Taiwan time (GMT+8).

Deadline for Title/Abstract Submission (Extension)	Nov. 01, 2021
Deadline for Camera-Ready Paper Submission (Extension)	Nov. 15, 2021
Notification of Acceptance	Dec. 30, 2021
Deadline for Final Paper (IEEE compatible version) Submission	Jan. 31, 2022
Deadline for Author Registration Deadline	Feb. 28, 2022

2022 Technical Program Co-Chairs

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